



# PATENT

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE


Docket No.: SCHMITT-16

In re Application of:	)
THEODORE SCHMITT ET AL.	)
Appl. No.: 10/706,864	)
Filed: November 12, 2003	)
For: STRUCTURE FOR HEAT DISSIPATION	)

## INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

S I R:

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450", on <u>January 8, 2004</u> .	
(Date)	
<u>HENRY M. FEIEREISEN</u>	
Name of Registered Representative	
	<u>1-8-2004</u>
Signature	Date of Signature

In accordance with 37 C.F.R. 1.56, applicant wishes to call the attention of the Examiner to the following references A) to H) which were cited in the instant specification and to reference I). Applicant does not admit that any of the cited documents constitutes prior art against the pending application.

	Country:	Patent or Appl. No:	Patentee or Applicant:	Issue or Filing Date:
A)	D.D.L. Chung: "Materials for thermal conduction"			03-15-2000
B)	Ting et al.: "Composites based on thermally .."			09-29-1994
C)	USA	6,460,597	McCullough et al	10-08-2002
D)	USA	5,660,923	Bieler et al.	08-26-1997
E)	USA	6,469,381	Houle et al.	10-22-2002
F)	USA	6,406,790	Ushijima	06-18-2002
G)	USA	5,578,543	Tennent et al.	11-26-1996
H)	USA	5,814,408	Ting et al.	09-29-1998
I)	Austria	AT 408 345 B	Schmitt	11-17-1999

Copies of references A), B) and I) are submitted herewith along with form PTO-1449. The Examiner is requested to initial the attached form PTO-1449 and to return a copy of the initialed document to the undersigned as an indication that the attached references have been considered and made of record.

☒ This Information Disclosure Statement is filed within three months of the filing date of a national application other than a continued prosecution application under 1.53(d), so that no fee under 37 C.F.R. §1.97 is due.

☐ This Information Disclosure Statement is filed within three months of the date of entry of the national stage as set forth in 1.491 in an international application, so that no fee under 37 C.F.R. §1.97 is due.

☐ This Information Disclosure Statement is filed before the mailing of a first Office Action on the merits, so that no fee under 37 C.F.R. §1.97 is due.

☐ This Information Disclosure Statement is filed before the mailing of a first Office Action after the filing of a request for continued examination under §1.114, so that no fee under 37 C.F.R. §1.97 is due.

☐ This Information Disclosure Statement is filed after the issuance of a first office but before issuance of a final action under §1.113, or a notice of allowance under §1.311.

☐ This Information Disclosure Statement is submitted after the mailing of a final action or a notice of allowance, but before payment of the issue fee.

☐ The undersigned submits the following statement requesting consideration of this statement:

The undersigned hereby states:

☐ That each item of information contained in the information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of the information disclosure statement;

☐ That no item of information contained in the information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application, and, to the knowledge of the person signing the statement after making reasonable inquiry, no item of information contained in the information disclosure statement was known to any individual designated in §1.56(c) more than three months prior to the filing of the information disclosure statement.

☐ The fee of \$180.00 set forth in 1.17(p).

☐ The Commissioner is hereby authorized to charge the fee as set forth in 1.17(p), and any additional fees which may be required, or credit any overpayment to Deposit Account No. 06-0502.

[X] The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Deposit Account No. 06-0502.

In order to satisfy the requirement under 37 C.F.R. §1.98(a)(3) for a concise explanation of the relevance of each item of information, applicant herewith notes with respect to any information that is not in English language as follows:

Reference 1) describes a process for securing a body of metal matrix composite to a ceramic body coated with a metal, whereby the ceramic body is placed onto the MMC body, and both bodies are heated above the eutectic temperature of the system consisting of the MMC body and the ceramic body, and then allowed to cool down at room temperature.

The above-identified application discloses and claims an invention patentable over this prior art.

Entry of the references above set forth into the file of the above application is believed to be in order and is respectfully requested.

Respectfully submitted

By:   
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Reg. No. 31,084

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Form PTO-1449

U.S. Department of Commerce  
Patent and Trademark Office

## INFORMATION DISCLOSURE CITATION

<b>Attorney's Docket No.</b> SCHMITT-16	<b>Applicant</b> Theodore Schmitt et al.	<b>Appl. No.</b> 10/706,864
<b>Filing Date</b> November 12, 2003	<b>Group</b>	<b>Examiner</b>

## U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date, if appropriate
	6,460,597	10-08-2002	McCullough			
	5,660,923	08-26-1997	Bieler et al			
	6,469,381	10-22-2002	Houle et al.			
	6,406,790	06-18-2002	Ushijima			
	5,578,543	11-26-1996	Tennent et al.			
	5,814,408	09-29-1998	Ting et al.			

## FOREIGN PATENT DOCUMENTS

Document Number	Date	Country	Class	Subclass	Translation
AT 408 345 B	11-17-1999	Austria			No

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	D.D.L. Chung: "Materials for thermal conduction", in: Applied Thermal Engineering 21, pages 1593-1605, March 15, 2000
	J.-M. Ting et al.: "Composites based on thermally hyper-conductive vapor grown carbon fiber", in: J. Mater. Res., Vol. 10, No.6, June 1995, pages 1478-1484

Examiner:

Date considered:

\*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.